SCAS302G - JANUARY 1993 - REVISED JUNE1998

- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 2 V at V_{CC} = 3.3 V, T_A = 25°C
- Power Off Disables Outputs, Permitting Live Insertion
- Support Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- ESD Protection Exceeds 2000 V Per MIL-STD-833, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW)
 Packages, and Ceramic Chip Carriers (FK)

description

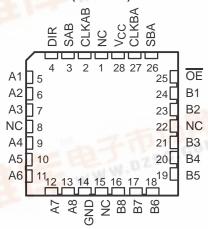
The SN54LVC646A octal bus transceiver and register is designed for 2.7-V to 3.6-V V_{CC} operation and the SN74LVC646A octal bus transceiver and register is designed for 1.65-V to 3.6-V V_{CC} operation.

These devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that are performed with the 'LVC646A.

SN74LVC646A . . . DB, DW, OR PW PACKAGE (TOP VIEW)



SN54LVC646A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

Output-enable (\overline{OE}) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port is stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. DIR determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data is stored in one register and B data can be stored in the other register.

When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TPIC is a trademark of Texas Instruments Incorporated.



SCAS302G - JANUARY 1993 - REVISED JUNE1998

description (continued)

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54LVC646A is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVC646A is characterized for operation from -40° C to 85° C.

FUNCTION TABLE

		INP	UTS			DAT	A I/O	OPERATION OR FUNCTION
ŌĒ	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified [†]	Store A, B unspecified [†]
Х	X	Χ	\uparrow	Χ	Χ	Unspecified [†]	Input	Store B, A unspecified [†]
Н	Х	1	↑	Х	Х	Input	Input	Store A and B data
Н	X	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Χ	L	Χ	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

[†] The data-output functions can be enabled or disabled by various signals at $\overline{\mathsf{OE}}$ and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



SCAS302G - JANUARY 1993 - REVISED JUNE1998

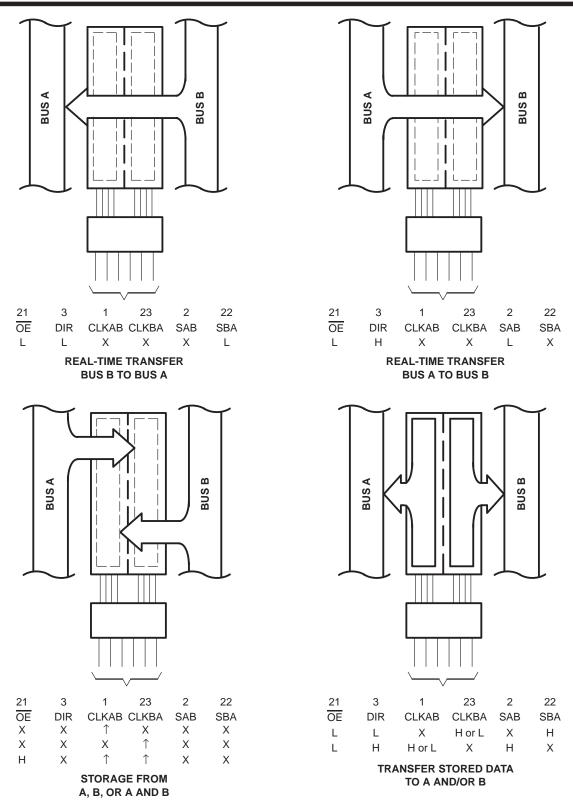
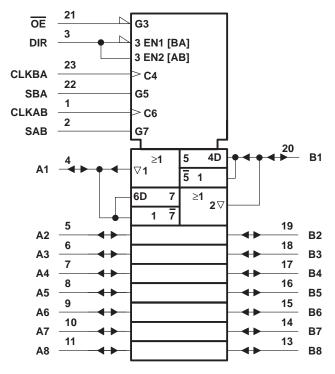


Figure 1. Bus-Management Functions



SCAS302G - JANUARY 1993 - REVISED JUNE1998

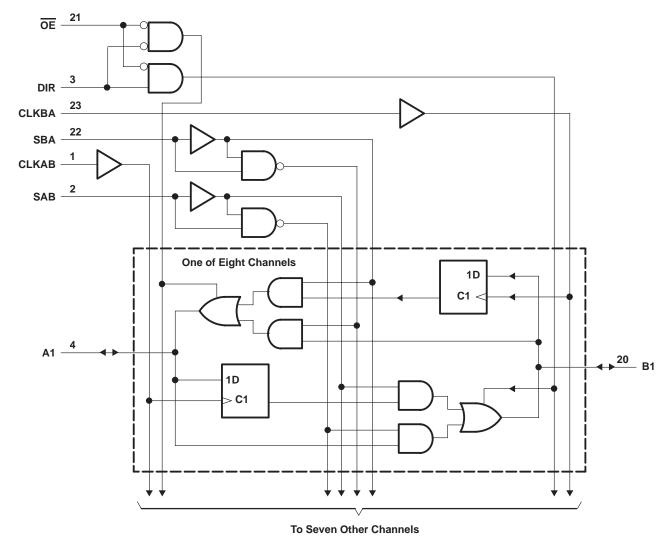
logic symbol†



 $^{^\}dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, and PW packages.



logic diagram (positive logic)



Pin numbers shown are for the DB, DW, and PW packages.

SCAS302G - JANUARY 1993 - REVISED JUNE1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Voltage range applied to any output in the high-imp	edance or power-off state, VO
Voltage range applied to any output in the high or le	
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
	±50 mA
Continuous current through V _{CC} or GND	±100 mA
	B package 104°C/W
	V package 81°C/W
PV	V package 120°C/W
	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of $V_{\hbox{CC}}$ is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			SN54L	/C646A	SN74L\	/C646A		
			MIN	MAX	MIN	MAX	UNIT	
V	Cumply valtage	Operating	2	3.6	1.65	3.6	V	
VCC	Supply voltage	Data retention only	1.5		1.5		ľ	
		V _{CC} = 1.65 V to 1.95 V			0.65×V _{CC}			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V			1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2		2		1	
		V _{CC} = 1.65 V to 1.95 V				0.35×V _{CC}		
V_{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V				0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		0.8	1	
٧ _I	Input voltage		0	5.5	0	5.5	V	
\/ -	Output valtage	High or low state	0	Vcc	0	VCC	V	
VO	Output voltage	3 state	0	5.5	0	5.5	ľ	
		V _{CC} = 1.65 V				-4		
1	High level cutout current	V _{CC} = 2.3 V				-8	mA	
ЮН	High-level output current	V _{CC} = 2.7 V		-12		-12	IIIA	
		V _{CC} = 3 V		-24		-24	1	
		V _{CC} = 1.65 V				4		
1	Love lovel output ourrent	V _{CC} = 2.3 V				8	mA	
lOL	Low-level output current	V _{CC} = 2.7 V				12	mA	
		V _{CC} = 3 V		24		24		
Δt/Δν	Input transition rise or fall rate		0	10	0	10	ns/V	
ТД	Operating free-air temperature		-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCAS302G - JANUARY 1993 - REVISED JUNE1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DA	DAMETER	TEST CONDITIONS		SN54	LVC646	4	SN74	LVC646	4	UNIT	
PARAMETER		TEST CONDITIONS	v _{CC}	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII	
		ΙΟΗ = -100 μΑ	1.65 V to 3.6 V				V _{CC} -0.2				
		ΙΟΗ = -100 μΑ	2.7 V to 3.6 V	V _{CC} -0.2							
Voн	I _{OH} = -4 mA	1.65 V				1.2					
	I _{OH} = –8 mA	2.3 V				1.7			V		
		I _{OH} = -12 mA	2.7 V	2.2			2.2				
		10H = -12 IIIA	3 V	2.4			2.4				
		I _{OH} = -24 mA	3 V	2.2			2.2				
		I _{OL} = 100 μA	1.65 V to 3.6 V						0.2		
		ΙΟΣ = 100 μΑ	2.7 V to 3.6 V			0.2					
V _{OL}		I _{OL} = 4 mA	1.65 V						0.45	V	
		$I_{OL} = 8 \text{ mA}$	2.3 V						0.7		
		$I_{OL} = 12 \text{ mA}$	2.7 V			0.4			0.4		
		$I_{OL} = 24 \text{ mA}$	3 V			0.55			0.55		
Ц	Control inputs	$V_{I} = 0 \text{ to } 5.5 \text{ V}$	3.6 V			±5			±5	μΑ	
l _{off}		V _I or V _O = 5.5 V	0						±10	μΑ	
l _{OZ} ‡		V _O = 0 to 5.5 V	3.6 V			±15			±10	μΑ	
		V _I = V _{CC} or GND	0.01/			10			10	•	
lcc		$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}$ $I_{\text{O}} = 0$	3.6 V			10			10	μΑ	
Δl _{CC}		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500			500	μА	
Ci	Control inputs	$V_I = V_{CC}$ or GND	3.3 V		4.5			4.5		pF	
Cio	A or B ports	$V_O = V_{CC}$ or GND	3.3 V		7.5			7.5		pF	

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

			SN54LV	/C646A		
		V _{CC} =	2.7 V	V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	
fclock	Clock frequency		150		150	MHz
t _W	Pulse duration	3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	1.6		1.5	·	ns
t _h	Hold time, data after CLK↑	1.7		1.7		ns

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

[§] This applies in the disabled state only.

SCAS302G - JANUARY 1993 - REVISED JUNE1998

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 4)

			SN74LVC646A							
			1.8 V 5 V	V _{CC} =		VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		†		†		150		150	MHz
t _W	Pulse duration	†		†		3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	†		†		1.6		1.5		ns
th	Hold time, data after CLK↑	†		†		1.7		1.7		ns

[†] This information was not available at the time of publication.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =	2.7 V	V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
f _{max}			150		150		MHz
	A or B	B or A		7.9	1	7.4	
^t pd	CLK	A or B		8.8	1	8.4	ns
	SBA or SAB	AUIB		9.9	1	8.6	
t _{en}	ŌĒ	А		10.2	1	8.2	ns
^t dis	ŌĒ	А		8.9	1	7.5	ns
t _{en}	DIR	В		10.4	1	8.3	ns
^t dis	DIR	В		8.7	1	7.9	ns

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 4)

		TO (OUTPUT)	SN74LVC646A								
PARAMETER	FROM (INPUT)		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fmax			†		†		150		150		MHz
	A or B	B or A	†	†	†	†		7.9	1.4	7.4	
^t pd	CLK	A or B	†	†	†	†		8.8	1.3	8.4	ns
	SBA or SAB		†	†	†	†		9.9	1.4	8.6	
t _{en}	ŌĒ	А	†	†	†	†		10.2	1	8.2	ns
^t dis	ŌĒ	А	†	†	†	†		8.9	1	7.5	ns
^t en	DIR	В	†	†	†	†		10.4	1.2	8.3	ns
^t dis	DIR	В	†	†	†	†		8.7	1.1	7.9	ns

[†]This information was not available at the time of publication.

SN54LVC646A, SN74LVC646A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS SCAS302G - JANUARY 1993 - REVISED JUNE1998

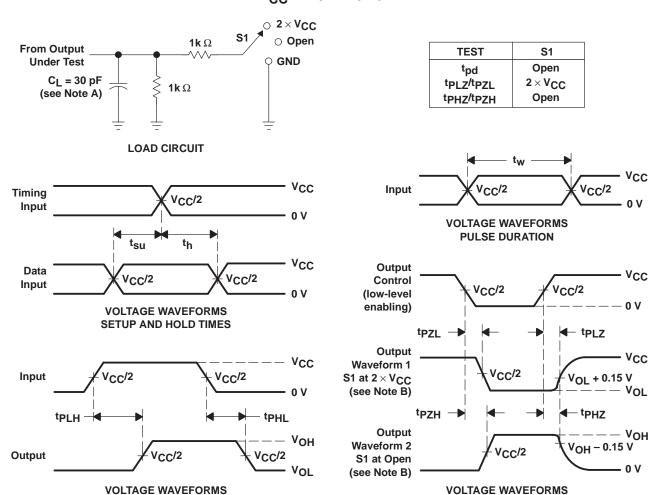
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V ± 0.15 V	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT	
			CONDITIONS	TYP	TYP	TYP	
Const	Power dissipation capacitance	dissipation capacitance Outputs enabled		†	†	75	pF
C _{pd}	per transceiver	Outputs disabled	f = 10 MHz	†	†	9	рг

[†] This information was not available at the time of publication.

SCAS302G - JANUARY 1993 - REVISED JUNE1998

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq$ 2 ns. $t_f \leq$ 2 ns.

ENABLE AND DISABLE TIMES

- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.

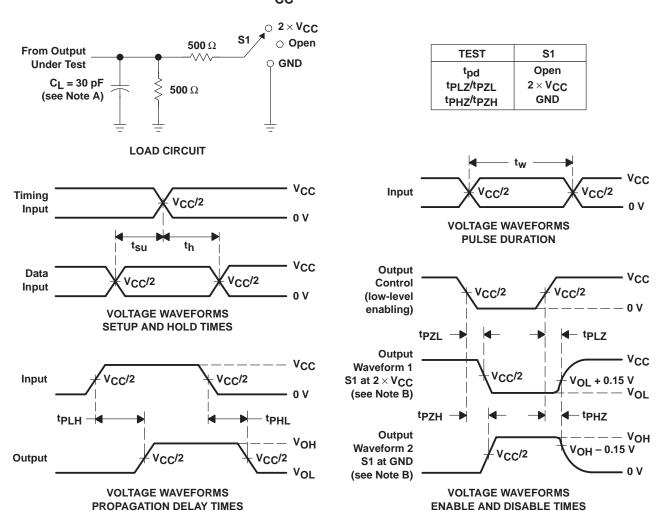
PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

SCAS302G - JANUARY 1993 - REVISED JUNE1998

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



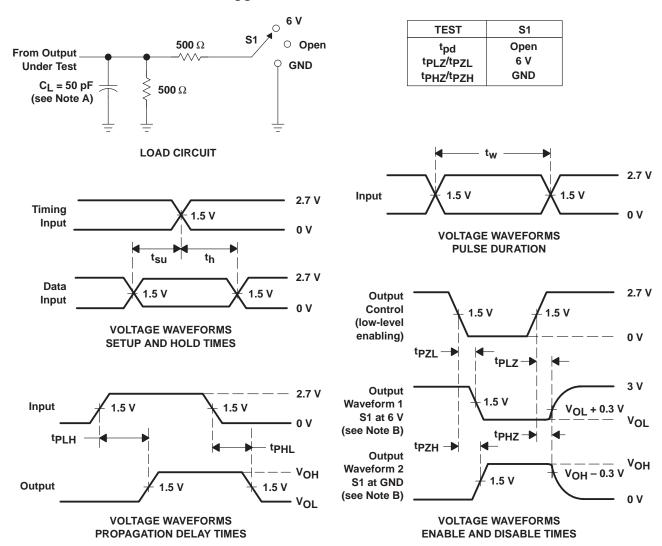
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



SCAS302G - JANUARY 1993 - REVISED JUNE1998

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.

Copyright © 1998, Texas Instruments Incorporated